

15 g PC/ABS
Lower casing for mobile telephone

Key data

Molded part	Lower casing
Application	Mobile telephone
Part weight	15 g
Material	PC/ABS
Mold type	Multi-cavity mold
No. of cavities	2

Illustrations simplified, schematically drawn and not to scale.
For a specific application, please consult Synventive.

Customer's requirements

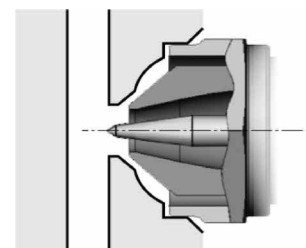
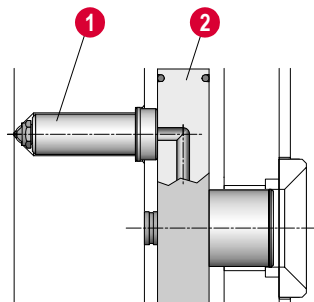
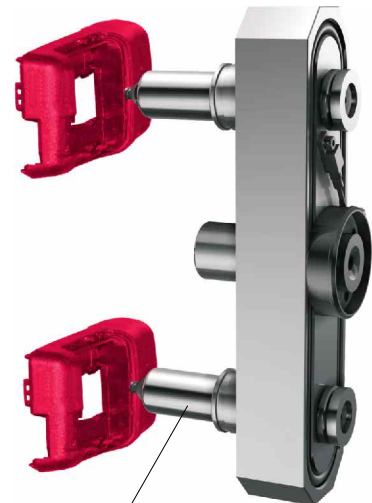
This application involved the production of lower casings for mobile telephones of PC/ABS. The cavities were to be directly gated via the hot runner to the molding surface in a spherical dimple.

Solution

In the implementation of this application, an externally heated 2-port hot runner system with face fit manifold nozzles was employed. The cavity was directly gated with the hot runner to the molding surface via open nozzles with torpedo, whereby the gate was recessed in a spherical dimple.

Benefits

- Production without sprue waste and without reworking
- Good gating quality with respect to separation and appearance
- Uniform supply and filling of all cavities with melt
- Good molding quality from all the cavities



Schematic product overview

1. Manifold nozzle, face fit
Series CB...M, Type WT
2. Manifold
Series VC

07 C + V C

W T